

What is claimed is:

1. A pedestal for a semiconductor processing chamber, comprising:
 - a first body comprising a ceramic material that includes a first surface, wherein a plurality of heater elements are encapsulated within the first body; and
 - a second body comprising a ceramic material that comprises one or more continuously curved grooves formed in one or more surfaces of the second body, andwherein the first body is coupled to the second body, and the first surface of the first body is positioned to enclose a region that is defined by the grooves formed in the one or more surfaces of the second body and a portion of the first surface, wherein one of more of the one or more continuously curved grooves has a constant radius, and wherein the continuously curved groove has a radius of between about 0.5 inches and 50.0 inches.
2. A pedestal for a semiconductor processing chamber, comprising:
 - a first body comprising a ceramic material and a second body comprising a ceramic material;
 - a plurality of heater elements encapsulated within the first body;
 - one or more continuously curved grooves are formed in one or more surfaces of the first body or the second body, wherein the first body is coupled to the second body and encloses the grooves; and
 - a temperature monitoring device disposed within the one or more continuously curved grooves, wherein one of more of the one or more continuously curved grooves has a constant radius, and wherein the continuously curved groove has a radius of between about 0.5 inches and 50.0 inches.